

Title (en)

Electroless nickel-boron plating.

Title (de)

Stromlose Nickel-Bor-Plattierung.

Title (fr)

Placage sans courant avec nickel-bore.

Publication

EP 0073583 A1 19830309 (EN)

Application

EP 82304210 A 19820810

Priority

US 29552381 A 19810824

Abstract (en)

The boron content of an electroless nickel-boron deposit is enhanced by including in the bath a source of zirconyl ions or vanadyl ions, which bath can be operated at moderate temperature and pH despite the fact that boranes can be used as reducing agents. The deposit laid down has a boron content of at least about 2 weight %, based on the total weight of the deposit. The source of the ions may be for example zirconyl chloride, vanadyl sulfate or sodium metavanadate at a concentration between 0.001 and 0.1 mol per liter of the bath.

IPC 1-7

C23C 3/02

IPC 8 full level

H05K 3/18 (2006.01); **C23C 18/32** (2006.01); **C23C 18/34** (2006.01)

CPC (source: EP)

C23C 18/34 (2013.01)

Citation (search report)

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